

APPLICATION DATA SHEET

Electronic Version v14
Stylesheet Version v14.1

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Application Information:

Title of Invention: BRITTLE SUBSTRATE CUTTING SYSTEM AND BRITTLE
SUBSTRATE CUTTING METHOD

Application Type: regular, utility

Attorney Docket Number: 49288.1600

Botanic Information:

Publication Information:

Suggested Figure for Publication -

Suggested Classification -

Suggested Technology Center -

Total Number of Drawing Sheets - 22

Representative Information:

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Domestic Priority Information:

This is a National Stage of US application number PCT/JP2004/006103, filed 2004-04-27, now Pending.

Foreign Priority Information:

Doc.No:2003-124501; Country - JP; Date: 2003-04-28 us-priority-claimed

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